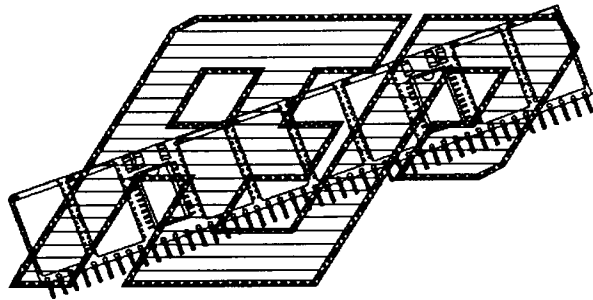


- >> 1,048,576 x 16 Organization
- >> On board Registers for all address and chip enable lines.
- >> Double sided to maximize bit density
- >> Completely Static operation
- >> TTL compatible
- >> Uses single +5V power supply



**1 MEGAWORD BY 16 BIT HIGH SPEED
STATIC RAM MODULE WITH ON-BOARD REGISTERS**

DESCRIPTION:

The AEPSS1M16 is a high speed, high density 1 megaword by 16 bit static random access memory module with on board registers. The registers on the module allow for high speed pipelining, which is ideal for use in today's high speed microprocessor systems that require quick and reliable memory.

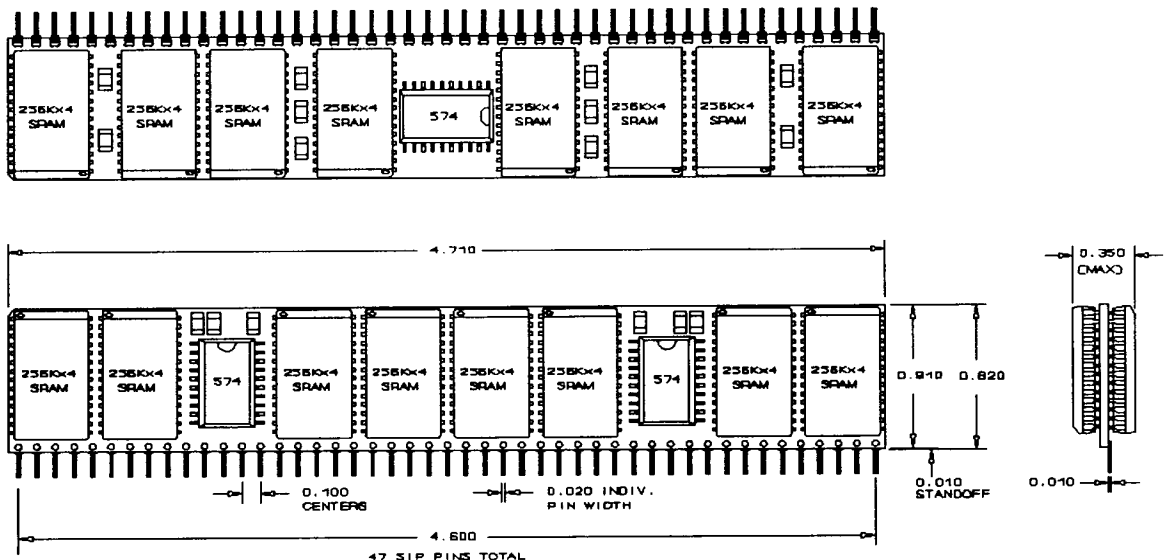
Performance specifications and electrical characteristics are determined by the IC devices used. A typical memory component module will draw 0.8mW (typical) in standby mode and 2800mW (typical) during access.

The module can use any 256Kx4 SRAM ICs with SOJ lead packages and standard pin-out made by any of variety of manufacturers in both Mix-CMOS technologies. A wide range of access speeds are available. The register normally used is the 74F574, please check with AEP for the availability and compatibility of other technologies.

Physically it consists of an FR4 PC material substrate surface mounted with sixteen 256Kx4 high speed SRAM ICs, three 74F574 ICs, sixteen 0.10 microfarad decoupling capacitors, and 47 press-in I/O pins in a single in-line packaging (SIP) format. Mechanical dimensions are 0.820 in. high by 4.710 in. long by 0.350 in. wide. The SIP I/O pins are on 0.1 inch center spacing.

**SPECIFICATION DRAWING
1M x 16 SRAM MODULE**

DIMENSIONS IN INCHES, TOLERANCE: +/- 0.010 UNLESS SPECIFIED.

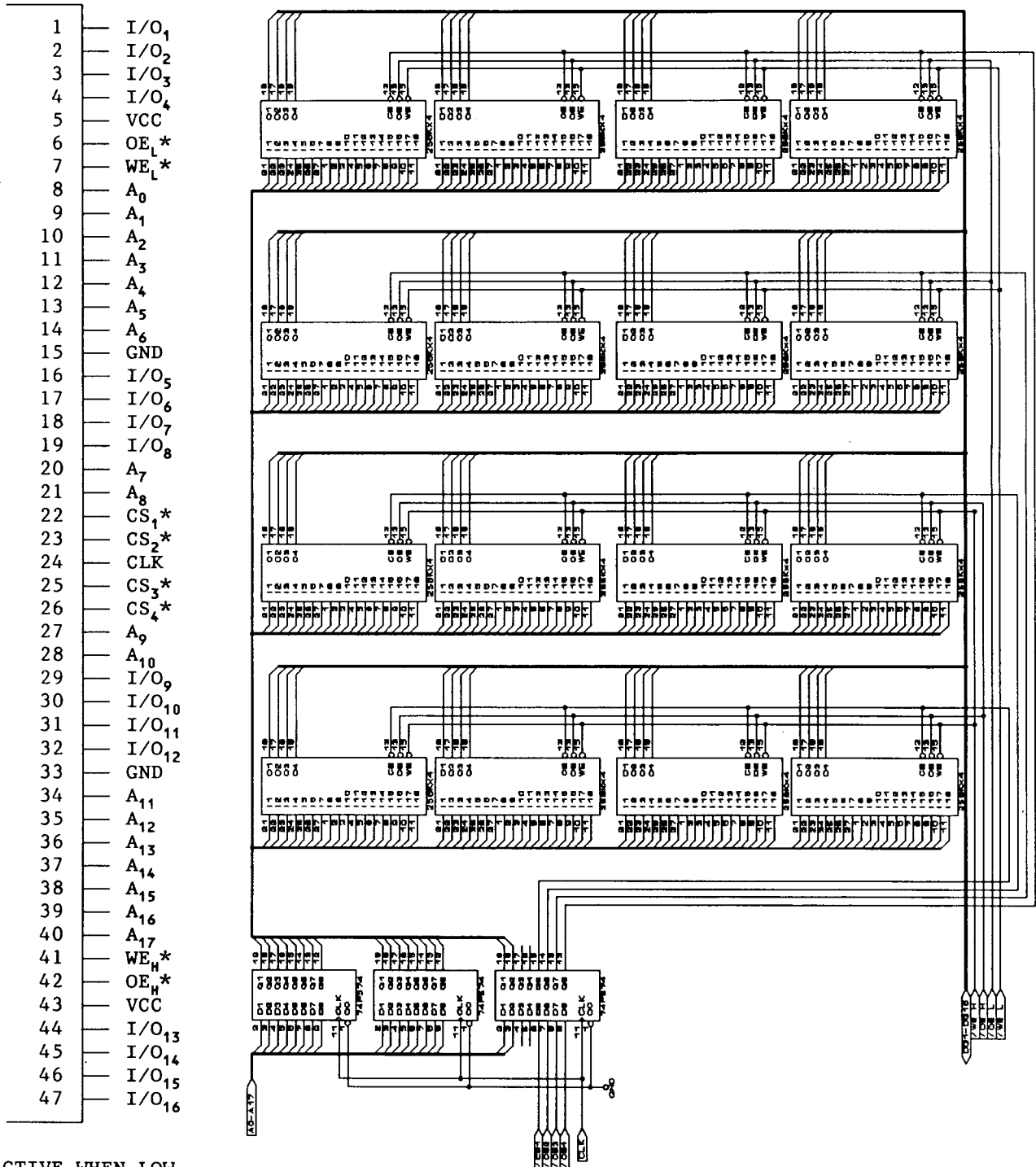


ADVANCED ELECTRONIC PACKAGING

1M x 16 STATIC RAM MODULE

SIP PIN-OUT CONFIGURATION

FUNCTIONAL DIAGRAM



ADVANCED ELECTRONIC PACKAGING